

CQSFP-S-LR-LC-1310-10-DDM QSFP+ 40G LR4 Transceiver

Features

Hot Pluggable QSFP+ form factor Operating Data Rate up to 41.2Gb/s Duplex LC Connector Interface Up to 10Km over SMF 4x10Gbps DFB-based CWDM transmitter PIN and TIA array on the receiver side 4x10G electrical interface Single 3.3V Power Supply Power dissipation <3.5W Operating case temperature range: -20°C to 70°C Compliant with SFF-8679 Compliant with SFF-8636 Compliant with IEEE802.3ba-2010

Applications

- 40G Ethernet
- Data Center and LAN

General Description

CQSFP-S-LR-LC-1310-10-DDM QSFP+ LR4 is designed to operate over single-mode fiber system using 4X10 CWDM channel in 1310 band and links up to 10km. The module converts 4 inputs channel of 10Gb/s electrical data to 4 CWDM optical signals, and multiplexes them into a single channel for 40Gb/s optical transmission. Reversely, on the receiver side, the module optically de-multiplexes a 40Gb/s input into 4 CWDM channels signals, and converts them to 4 channel output electrical data.

Part Number Ordering Information

Part NO.	Data Rate	Fiber	Distance	Interface	Temp.
CQSFP-S-LR-LC-1310-10-DDM	41.2Gb/s	SMF	10Km	LC	-20~70°C

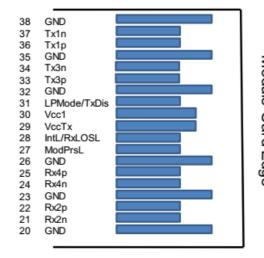


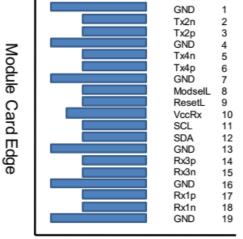
Electrical Connector

The following figure shows the signal symbols and pad numbering for the module edge connector. The diagram shows the module PCB edge as a top and bottom view, where bottom is nearer the host PCB. There are 38 pads intended for high speed signals, low speed signals, power and ground connections.

The module contains a printed circuit board that mates with the electrical connector. The pads are designed for a sequenced mating:

Connected first, disconnected last: - ground contacts Connected second, disconnected second: - power contacts Connected third, disconnected first: - signal contacts





Top Side Viewed From Top

Bottom Side Viewed From Bottom

Pin Description

Pad	Logic	Symbol	Description	Plug Seq.	Note
1		GND	Ground	1	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3	
4		GND	Ground	1	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3	
7		GND	Ground	1	1
8	LVTTL-I	ModSelL	Module Select	3	
9	LVTTL-I	ResetL	Module Reset	3	
10		VccRx	+3.3V Power Supply Receiver	2	2
11	LVCMOS-I/O	SCL	Two-wire interface clock	3	
12	LVCMOS-I/O	SDA	Two-wire interface data	3	
13		GND	Ground	1	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	



16		GND	Ground	1	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	1
20		GND	Ground	1	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3	
23		GND	Ground	1	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3	
26		GND	Ground	1	1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL /RxLOSL	Interrupt. Optionally configurable as RxLOSL via SFF-8636	3	
29		VccTx	+3.3V Power supply transmitter	2	2
30		Vcc1	+3.3V Power supply	2	2
31	LVTTL-I	LPMode /TxDis	Low Power Mode. Optionally configurable as TxDis via SFF-8636	3	
32		GND	Ground	1	1
33	CML-I	Тх3р	Transmitter Non-Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3	
35		GND	Ground	1	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3	
38		GND	Ground	1	1

Note 1: GND is the symbol for signal and supply (power) common for the module. All are common within the module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2: VccRx, Vcc1 and VccTx are applied concurrently and may be internally connected within the module in any combination.



Absolute Maximum Ratings

Exceeding any one of these values may damage the device permanently.

Parameter	Symbol	Min.	Typical	Max.	Unit
Supply Voltage	V _{cc}	-0.5		3.6	V
Storage Temperature	Τ _s	-40		+85	°C
Operating Relative Humidity	RH			85	%
Receiver Damage Threshold, per Lane	P_{Rdmg}	5.5			dBm

Recommended Operating Environment

Parameter	Symbol	Min.	Typical	Max.	Unit
Case operating Temperature	T _{op}	-20		70	°C
Supply Voltage	V _{cc}	3.135	3.3	3.465	V
Power Dissipation	P _D			3.5	W

Electrical Characteristics

Parameter	Symbol	Min	Тур	Max	Unit	Note		
Data rata		10.3	10.31250±100ppm		Gbps			
Transmitter								
Differential data input swing	V _{in}			900	mVpp			
Input Impedance (Differential)	Z _{in}	90	100	100	ohm			
Eye width		0.46			UI			
Eye height		95			mV			
DC common mode voltage		-350		2850	mV			
	Re	ceiver						
Differential output amplitude		200		900	mVpp			
Output Impedance (Differential)	Z _{out}	90	100	110	ohm			
Eye width		0.57			UI			
Eye height differential		228			mV			
Vertical eye closure				5.5	dB			

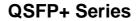


Optical Characteristics

Param	eter	Symbol	Min	Тур	Max	Unit	Note
Data ı	rata		10.3	1250 ± 100	100ppm Gbps		
	Lane1	λ _{C1}	1264.5	1271	1277.5	•	
Center	Lane2	λ _{C2}	1284.5	1291	1297.5		
Wavelength	Lane3	λ _{C3}	1304.5	1311	1317.5	nm	
	Lane4	λ _{C4}	1324.5	1331	1337.5		
		Trai	nsmitter	1	1	1	I
Total Average (Output Power	PT			8.5	dBm	
Average Launch P	ower each Lane	AOP	-7		2.3	dBm	
Optical Modulation Lan	-	OMA	-4		3.5	dBm	
Extinction	n Ratio	ER	3.5			dB	
Transmitter and dis each l	ane	TDP			2.2	dB	
Launch power in C each I			-2.3			dBm	
Side-mode Sup	pression ratio	SMSR	30			dB	
Relative Intensity Noise		RIN			-130	dB/Hz	
Transmitter F		TR			-12	dB	
Transmitter eye mask definition {X1, X2, X3, Y1, Y2,Y3 }			{0.25, 0.4,		3		
		Re	eceiver	1	1	1	r
Average Receive F	ower each Lane	RXAOP	-13.7		2.3	dBm	
Receive Power (C	1	RXOMA			3.5	dBm	
Receive Sensit each L	ane	RXSEN			-11.5	dBm	
Stressed Receiv (OMA) eae	•	RXSRS			-9.6	dBm	4
Optical Ret	urn Loss	ORL			-26	dB	
LOS A	ssert	LOSA	-28			dBm	
LOS De-	Assert	LOSD			-15	dBm	
LOS Hys	teresis		0.5			dB	
Conditions of stress	sed receiver sensi	tivity test					
Vertical eye clo	sure penalty	VECP		1.8		dB	
Stressed ey	e J2 Jitter	J2		0.3		UI	
Stressed ey	e J9 Jitter	J9		0.47		UI	

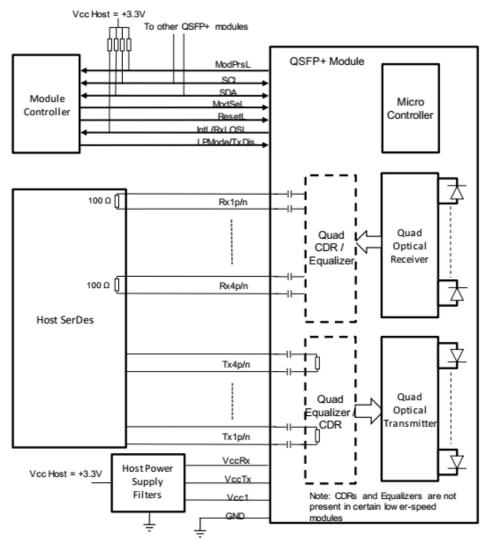
Note 3: Hit ratio 1x10⁻¹²

Note 4: Measured with conformance test signal at TP3 for BER = 10^{-12}





Recommend Circuit Schematic





Mechanical Specifications

